VXD Status: R&D and SW Description

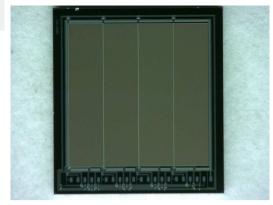
LCWS11/Granada - 28 Septembre 2011

Contents

- R&D status and DBD related perspectives
 - * sensors (DEPFET, FPCCD, CMOS)
 - * integration issues (ladders, global detector)
- Description of VXD in simulation
 - * ladders and mechanical support
 - * services, periphery
- Summary

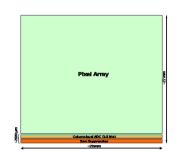
Progress on Sensor R&D

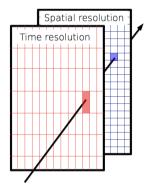
- Delayed read-out : FPCCD
 - * Proto.4 fab. in 2010 (6×6 mm²) with pixel pitch of 12, 9.6, 8 and 6 μm by tests under way by 50 μm thinning of proto. seems OK
 - * Proto.5 expected in FY 2012 : 1st large size chip ($\sim 1 \times 6 \text{ cm}^2$)
- Continuous read-out : DEPFET
 - * Devt mainly driven by BELLE-2 specifications (e.g. 50 μm pitch) \hookrightarrow sensors oriented towards VXD also part of wafers fabricated
 - * 50 μm thin sensors fabricated and partly tested (SNR) \hookrightarrow complete assessment of prototypes' performances under way
- Continuous read-out : CPS
 - strule Final archi. prototypes being fab. in 0.35 μm techno. :
 - \longrightarrow MIMO-30 (in: σ_{sp} & speed) / MIMO-31 (out: power)
 - ⇒ validation of sensors w.r.t. all VXD specs by Summer '12
 - * Translation from 0.35 μm to 0.18 μm techno. under way \hookrightarrow validation of sensor's architecture by Fall 2012
 - * Devt common to ALICE-ITS/MFT, CBM-MVD and AIDA-BT











Progress on System Integration

• Ladders:

- * 2-sided : PLUME coll. (based on CPS)
 - 1st proto. (0.6 % X0) fab. with 2×6 MIMOSA-26 sensors (12.7×1.1 cm 2) \hookrightarrow 8M pixels; \gtrsim 3 μm , 100 μs ; 300 kRad; 2· 10 12 n $_{eq}$ /cm 2 ; air cooled
 - sensors work as expected ⇒ beam tests in Nov.'11 (SPS)
 - 2nd proto will address mat. budget (0.3 % X0)
 - ← fab. & tested by Summer '12
- * Single-sided: DEPFET and CPS
 - → CPS sensor based ladders (0.37 %X0) in production for STAR-PXL
 - DEPFET based ladders being developed for BELLE-2
 - $-\!\!\!\!-\!\!\!\!-$ R&D on unsupported ladders (<0.15% X0) > SERNWIETE

Overal VXD integration :

- * DEPFETs preparing for BELLE-2 (installation by mid-2015)
- * CPS final prod. for STAR-PXL engineering proto. launched
- * 2-phase CO² cooling under study for FPCCD (-40°C, 100 W)

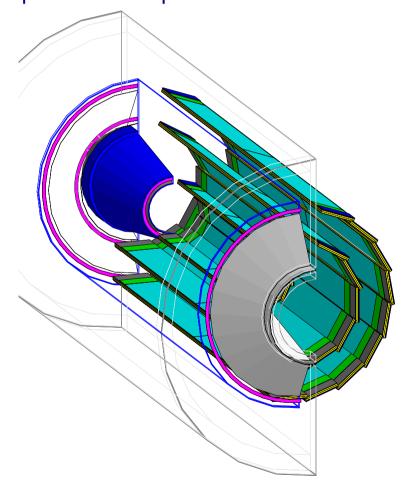






VXD Description in Simulation (1/2)

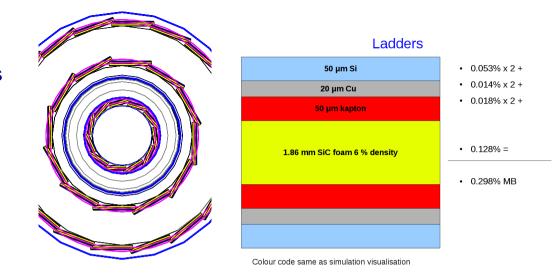
- "Hybrid" VXD description :
 - * Ladders: inspired by PLUME and CMOS sensor design
 - continuous (≡ fast) read-out with integrated data sparsification operated at room T
 - end of ladder material ≡ FPCCD
 - → cooling assumed by air flow
 - → Faraday cage (Al foil)
 - ★ Global mechanics & Services ≅ FPCCD design
 - gasket is closed → operation at low T
 - cooling services as for FPCCD
 - → cabling as for FPCCD
- Design definitely more realistic than for Lol
 - ⇒ more material ...



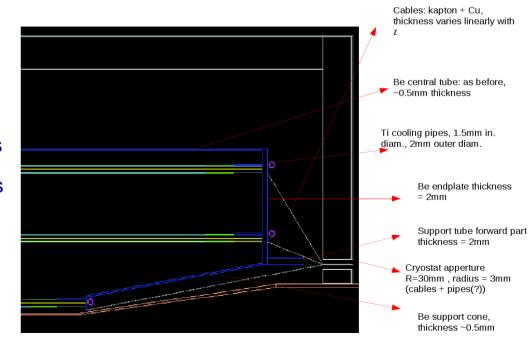
VXD Description in Simulation (2/2)

2-sided ladders and their supports :

- * material budget is \sim 0.3% X0 (LoI: 0.16% X0)
- * modified ladder fixings w.r.t. Lol
- * modified Be support:
 - \longrightarrow end plates' thickness (0.5 \longrightarrow 2 mm), holes
 - → clearance for pipes
 - closed enclosure
 - → modified supports w.r.t. beam pipe
- Services introduced according to FPCCD needs:
 - * cooling pipes & coolant distribution spiral at ladder ends
 - * cables from both sides (continous cones) & connections
- Work still on-going (G. Voutsinas)



Cryostat: styropor at 90mm, aluminium at 100mm (0.5mm thickness), as before



SUMMARY

Validation of VXD concept :

- * Sensors : requirements in speed, resolution, thickness, power, rad. tolerance likely to be met for DBD (continuous read-out approach)
- * Ladders: 2-sided approach validation & added-value assessment progressing well
 - \hookrightarrow though unlikely to go < 0.3 %X0 for DBD
- Services and global aspects: several issues being addressed
- ⇒ Concept significantly more trustable in DBD than in LoI (though not yet very well proven)

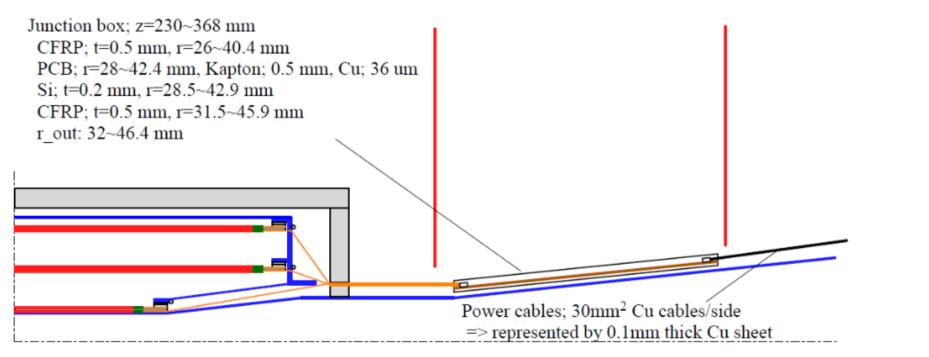
VXD description in simulation:

- * Active area: more detailed description than for Lol
- * Inactive areas of detector: clear progress in realism
- * Services outside detector : striking progress
- ⇒ Significantly more realistic description in DBD than in LoI (though incomplete)
- Developments expected to evolve fast in the coming 10-15 months
 - ⇒ try incorporating maximum of their outcome in the DBD

VXD Services: Junction Box

Junction box

- Flexible printed circuit (FPC) cables from the ladders are connected to the junction box using micro connectors
- The junction box (PCBs) are placed surrounding beam pipe
- Electronics parts on the PCB are represented by uniform 0.2mm-thick Si
- Power cables to the junction box have cross section of 30mm² in total



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